

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Sang Jin KIM	06/18/2009
Yongsoo OH	06/18/2009
Hwan-Soo LEE	06/18/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG ELECTRO-MECHANICS CO., LTD.
<b>Street Address:</b>	314 Maetan 3-Dong, Yeongtong-Gu
<b>City:</b>	Suwon, Gyunggi-do
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12503004
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<b>ATTORNEY DOCKET NUMBER:</b>	082658-0038
<b>NAME OF SUBMITTER:</b>	Soyeon (Karen) Pak Laub, Reg. No. 39,266
<b>Total Attachments: 2</b> source=082658-0038_Assignment#page1.tif source=082658-0038_Assignment#page2.tif	

CH \$40.00 12503004

Attorney Docket No.:

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- |                          |           |
|--------------------------|-----------|
| (1) <u>KIM, Sang Jin</u> | (5) _____ |
| (2) <u>OH, Yongsoo</u>   | (6) _____ |
| (3) <u>LEE, Hwan-Soo</u> | (7) _____ |
| (4) _____                | (8) _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG ELECTRO-MECHANICS CO., LTD.  
314 Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-do, Republic of Korea



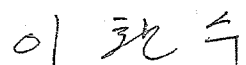
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled **FABRICATION METHOD OF THIN FILM DEVICE**

- (a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Application No. \_\_\_\_\_; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1)  Name: KIM, Sang Jin	<u>2009. 6. 18</u>
2)  Name: OH, Yongsoo	<u>2009. 6. 18</u>
3)  Name: LEE, Hwan-Soo	<u>2009. 6. 18</u>